| PCN Number:                        |                        |               | 20221213000.1 |               |                 |               |                                 | PCN Date:           |         | December 16,<br>2022 |         |
|------------------------------------|------------------------|---------------|---------------|---------------|-----------------|---------------|---------------------------------|---------------------|---------|----------------------|---------|
| Title                              | <b>:</b> :             | Qualification | of TI         | Malay         | sia a           | s a new Assen | nbly site for s                 | sele                | ct devi | ces                  |         |
| Cust                               | tome                   | r Contact:    | PCN A         | Manage        | <u>er</u>       | Dept:         | Quality Se                      | rvic                | es      |                      |         |
| Proposed 1 <sup>st</sup> Ship Date |                        |               | e:            | Mar 16, 2023  |                 |               | Sample Requests accepted until: |                     |         | 6, 2023*             |         |
| *Sa                                | mple r                 | ed aft        | ter Ja        | n 16,         | , 2023 will not | be supported  | d.                              |                     |         |                      |         |
| Cha                                | nge T                  |               |               |               |                 |               |                                 |                     |         |                      |         |
| $\boxtimes$                        | Assembly Site          |               |               | Design        |                 |               | Wafer Bump Site                 |                     |         |                      |         |
|                                    | Assembly Process       |               |               |               | Data Sheet      |               |                                 | Wafer Bump Material |         | p Material           |         |
| Assembly Materials                 |                        | ;             |               | Part number c |                 | change        |                                 | Wafe                | r Bum   | p Process            |         |
| Mechanical Specification           |                        |               |               |               | Test Site       |               |                                 | Wafer Fab Site      |         |                      |         |
| □ Packing/Shipping/Labeling        |                        |               |               | Test Process  |                 |               | Wafer Fab Materials             |                     |         |                      |         |
|                                    |                        |               |               |               |                 | <u>-</u>      | -                               |                     | Wafe    | r Fab                | Process |
|                                    | PCN Details            |               |               |               |                 |               |                                 |                     |         |                      |         |
| Doc                                | Description of Change: |               |               |               |                 |               |                                 |                     |         |                      |         |

## **Description of Change:**

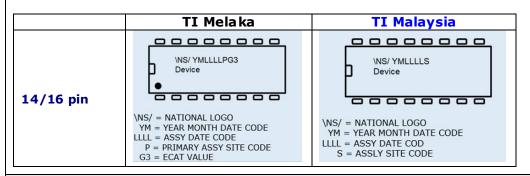
Texas Instruments Incorporated is announcing the qualification TIM (TI Malaysia) as a new Assembly Site for select devices listed in the "Product Affected" Section. Current assembly sites and Material differences are as follows.

| Assembly Site | Assembly Site<br>Origin | Assembly Country Code | Assembly Site City |
|---------------|-------------------------|-----------------------|--------------------|
| TI Melaka     | CU6                     | MYS                   | Mela ka            |
| TI Malaysia   | MLA                     | MYS                   | Kuala Lumpur       |

### **Material Differences:**

|                | TI Melaka | TI Malaysia |
|----------------|-----------|-------------|
| Mount compound | 210003    | 4147858     |
| Mold compound  | 150044    | 4211880     |
| Lead Finish    | Matte Sn  | NiPdAu      |

### **Package Marking Differences:**



### Reason for Change:

Continuity of supply.

Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):

None

**Impact on Environmental Ratings** 

Checked boxes indicate the status of environmental ratings following implementation of this change. If below boxes are checked, there are no changes to the associated environmental ratings.

| RoHS      | REACH     | Green Status | IEC 62474 |
|-----------|-----------|--------------|-----------|
| No Change | No Change | ☑ No Change  | No Change |

## Changes to product identification resulting from this PCN:

| Assembly Site |                            |          |
|---------------|----------------------------|----------|
| TI Melaka     | Assembly Site Origin (22L) | ASO: CU6 |
| TI Malaysia   | Assembly Site Origin (22L) | ASO: MLA |

Sample product shipping label (not actual product label)





(1P) \$N74L\$07N\$R (Q) 2000 (D) 0336 (31T)LOT: 3959047MLA (4W) TKY(1T) 7523483\$I2 (P) (2P) REV: (V) 0033317 (20L) C\$0: SHE (21L) CCO: USA (22L) A\$0: MLA (23L) ACO: MY\$

### **Product Affected:**

| LM380N/NOPB | LM384N/NOPB |
|-------------|-------------|
|-------------|-------------|

# **Qualification Report**

Approve Date 09-Dec-2022

## **Qualification Results**

Data Displayed as: Number of lots / Total sample size / Total failed

| Туре  | #  | Test Name                        | Condition  | Duration   | Qual Device:<br>LM384N/NOPB | QBS Reference:<br>LF444ACN/NOPB | QBS<br>Reference:<br><u>LM2594HVN-</u><br><u>ADJ/NOPB</u> |
|-------|----|----------------------------------|--|------------|-----------------------------|---------------------------------|---|
| HAST  | A2 | Biased HAST                      | 130C/85%RH   | 96 Hours   | -                           | -                               | 3/231/0   |
| UHAST | A3 | Autoclave                        | 121C/15psig  | 96 Hours   | 3/231/0                     | 3/231/0                         | 3/231/0   |
| TC    | A4 | Temperature Cycle                | -65C/150C  | 500 Cycles | 3/231/0                     | 3/231/0                         | 3/231/0   |
| HTSL  | A6 | High Temperature<br>Storage Life | 170C   | 420 Hours  | -                           | 3/231/0                         | 3/231/0   |
| WBS   | C1 | Ball Shear                       | 76 balls, 3 units min  | Wires      | 3/228/0                     | 3/228/0                         | 3/228/0   |
| WBP   | C2 | Bond Pull                        | 76 Wires, 3 units<br>min   | Wires      | 3/228/0                     | 3/228/0                         | 3/228/0   |
| SD    | C3 | PB-Free Solderability            | Precondition<br>w.155C Dry Bake<br>(4 hrs +/- 15<br>minutes); PB-Free<br>Solder; | -          | 3/66/0                      | 3/66/0                          | -   |
| PD    | C4 | Physical Dimensions              | (per mechanical drawing)   | -          | -                           | 3/15/0                          | 3/15/0  |

| CHAR | E5 | Electrical<br>Characterization | Side by Side, Test<br>parm comparison of<br>control vs. qual | - | 1/30/0 | 1/30/0 | 1/30/0 |  |
|------|----|--------------------------------|--|---|--------|--------|--------|--|
|------|----|--------------------------------|--|---|--------|--------|--------|--|

QBS: Qual By Similarity

Qual Device LM384N/NOPB is qualified at NOT CLASSIFIED NOT CLASSIFIED

Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable

The following are equivalent HTOL options based on an activation energy of 0.7eV: 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours

The following are equivalent HTSL options based on an activation energy of 0.7eV: 150C/1k Hours, and 170C/420 Hours The following are equivalent Temp Cycle options per JESD47: -55C/125C/700 Cycles and -65C/150C/500

Cycles Quality and Environmental data is available at TI's external Web site: http://www.ti.com/

Green/Pb-free Status: Qualified Pb-Free(SMT) and Green

# **Qualification Report**

Approve Date 05-Aug-2021

## **Qualification Results**

Data Displayed as: Number of lots / Total sample size / Total failed

|       |                                   | 2 4 44 2 .0                         | played as: Numb | 0. 00 .0 , .0 .0 | Qual       | 7 101011101100 | QBS        | QBS        |
|-------|-----------------------------------|-------------------------------------|-----------------|------------------|------------|----------------|------------|------------|
| Turns | Test Name /                       | Demotion                            | Qual Device:    | Qual Device:     | Device:    | Qual Device:   | Package    | Package    |
| Туре  | Condition                         | Duration                            | LF444ACN/NOPB   | LM231AN/NOPB     | LM2594HVN- | LMC6482IN/NOPB | Reference: | Reference: |
|       |                                   |                                     |                 |                  | ADJ/NOPB   |                | SN74HC595N | SN74LS03N  |
| AC    | Autoclave 121C                    | 96 Hours                            | 3/231/0         | 3/231/0          | 3/231/0    | 3/231/0        | 3/225/0    | 3/231/0    |
| ED    | Electrical<br>Characterization    | Per<br>Datasheet<br>Parameters      | Pass            | Pass             | Pass       | Pass           | Pass       | -          |
| HAST  | Biased HAST,<br>130C/85%RH        | 96 Hours                            | -               | -                | 3/231/0    | -              | -          | -          |
| HTSL  | High Temp<br>Storage Bake<br>170C | 420 Hours                           | 3/231/0         | 3/231/0          | 3/231/0    | 3/231/0        | 3/231/0    | 3/231/0    |
| LI    | Lead Fatigue                      | Leads                               | 3/27/0          | 3/54/0           | 3/36/0     | 3/54/0         | 3/45/0     | 3/45/0     |
| LI    | Lead Pull                         | Leads                               | 3/72/0          | 3/72/0           | 3/72/0     | 3/72/0         | 3/72/0     | 3/72/0     |
| PD    | Physical<br>Dimensions            | (per<br>mechanical<br>drawing)      | 3/15/0          | 3/15/0           | 3/15/0     | 3/15/0         | 3/15/0     | 3/15/0     |
| PKG   | Lead Finish<br>Adhesion           | Leads                               | 3/45/0          | -                | -          | -              | 3/45/0     | 3/45/0     |
| SD    | Solderability                     | Pb Free                             | 3/66/0          | 3/66/0           | -          | 3/66/0         | 3/66/0     | 3/66/0     |
| TC    | Temperature<br>Cycle, -65/150C    | 500 Cycles                          | 3/231/0         | 3/231/0          | 3/231/0    | 3/231/0        | 3/231/0    | 3/231/0    |
| VM    | Visual /<br>Mechanical            | (per mfg.<br>Site<br>specification) | 3/984/0         | 3/984/0          | 3/984/0    | 3/984/0        | 3/984/0    | 3/984/0    |
| WBP   | Bond Pull                         | Wires                               | 3/228/0         | 3/228/0          | 3/228/0    | 3/228/0        | 3/228/0    | 3/228/0    |
| WBS   | Ball Bond Shear                   | Wires                               | 3/228/0         | 3/228/0          | 3/228/0    | 3/228/0        | 3/228/0    | 3/228/0    |

<sup>-</sup> QBS: Qual By Similarity

- Qual Devices LF444ACN/NOPB, LM231AN/NOPB, LM2594HVN-ADJ/NOPB, LMC6482IN/NOPB is qualified at LEVEL1-NACG
- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable

- The following are equivalent HTOL options based on an activation energy of 0.7eV: 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
- The following are equivalent HTSL options based on an activation energy of 0.7eV: 150C/1k Hours, and 170C/420 Hours
- The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles Quality and Environmental data is available at Tl's external Web site: http://www.ti.com/

#### Green/Pb-free Status:

Qualified Pb-Free and Green

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

| Location                  | E-Mail                         |
|---------------------------|--------------------------------|
| WW Change Management Team | PCN www admin_team@list.ti.com |

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